Advance Information
Low-Voltage CMOS Quad 2-Input Multiplexer
With 5V-Tolerant Inputs (Non-Inverting)

MC74LCX157

LCX

LOW–VOLTAGE CMOS QUAD 2–INPUT MULTIPLEXER

The MC74LCX157 is a high performance, quad 2–input multiplexer operating from a 2.7 to 3.6V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5V allows MC74LCX157 inputs to be safely driven from 5V devices.

Four bits of data from two sources can be selected using the Select and Enable inputs. The four outputs present the selected data in the true (non–inverted) form. The MC74LCX157 can also be used as a function generator. Current drive capability is 24mA at the outputs.

- Designed for 2.7 to 3.6V V_{CC} Operation
- 5V Tolerant Inputs — Interface Capability With 5V TTL Logic
- LVTTL Compatible
- LVCMOS Compatible
- 24mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current (10µA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500mA
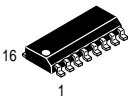- ESD Performance: Human Body Model >2000V; Machine Model >200V
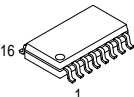

D SUFFIX
PLASTIC SOIC
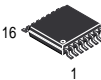CASE 751B–05

M SUFFIX
PLASTIC SOIC EIAJ
CASE 966–01
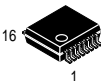
SD SUFFIX
PLASTIC SSOP
CASE 940B–03

DT SUFFIX
PLASTIC TSSOP
CASE 948F–01

Pinout: 16–Lead Plastic Package (Top View)

PIN NAMES

Pins	Function
I0n	Source 0 Data Inputs
I1n	Source 1 Data Inputs
E	Enable Input
S	Select Input
Zn	Outputs

REV 0.2

Ⓜ **MOTOROLA**

LOGIC DIAGRAM
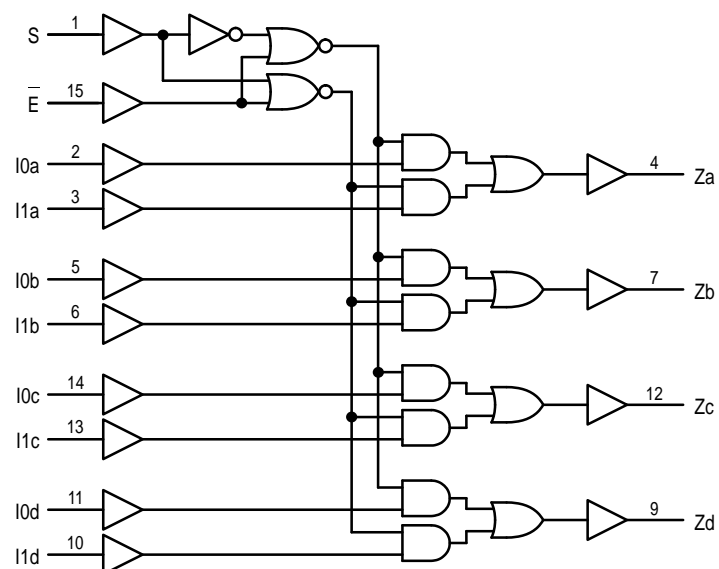
TRUTH TABLE

Inputs				Outputs
$\overline{E}$	S	I0n	I1n	Zn
H	X	X	X	L
L	H	X	L	L
L	H	X	H	H
L	L	L	X	L
L	L	H	X	H

H = High Voltage Level; L = Low Voltage Level; X = High or Low Voltage Level ; For I_{CC} Reasons DO NOT FLOAT Inputs

ABSOLUTE MAXIMUM RATINGS*

Symbol	Parameter	Value	Condition	Unit
V_{CC}	DC Supply Voltage	−0.5 to +7.0		V
V_I	DC Input Voltage	$-0.5 \leq V_I \leq +7.0$		V
V_O	DC Output Voltage	$-0.5 \leq V_O \leq V_{CC} + 0.5$[1]	Output in HIGH or LOW State	V
I_{IK}	DC Input Diode Current	−50	$V_I < GND$	mA
I_{OK}	DC Output Diode Current	−50	$V_O < GND$	mA
		+50	$V_O > V_{CC}$	mA
I_O	DC Output Source/Sink Current	±50		mA
I_{CC}	DC Supply Current Per Supply Pin	±100		mA
I_{GND}	DC Ground Current Per Ground Pin	±100		mA
T_{STG}	Storage Temperature Range	−65 to +150		°C

* Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute–maximum–rated conditions is not implied.

1. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	Operating	2.0	3.3	3.6	V
		Data Retention Only	1.5	3.3	3.6	
V_I	Input Voltage		0		5.5	V
V_O	Output Voltage	(HIGH or LOW State)	0		V_{CC}	V
I_{OH}	HIGH Level Output Current, $V_{CC} = 3.0V - 3.6V$				−24	mA
I_{OL}	LOW Level Output Current, $V_{CC} = 3.0V - 3.6V$				24	mA
I_{OH}	HIGH Level Output Current, $V_{CC} = 2.7V - 3.0V$				−12	mA
I_{OL}	LOW Level Output Current, $V_{CC} = 2.7V - 3.0V$				12	mA
T_A	Operating Free–Air Temperature		−40		+85	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate, V_{IN} from 0.8V to 2.0V, $V_{CC} = 3.0V$		0		10	ns/V

DC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic	Condition	$T_A = -40°C$ to $+85°C$		Unit
			Min	Max	
V_{IH}	HIGH Level Input Voltage (Note 1)	$2.7V \leq V_{CC} \leq 3.6V$	2.0		V
V_{IL}	LOW Level Input Voltage (Note 1)	$2.7V \leq V_{CC} \leq 3.6V$		0.8	V
V_{OH}	HIGH Level Output Voltage	$2.7V \leq V_{CC} \leq 3.6V$; $I_{OH} = -100\mu A$	$V_{CC} - 0.2$		V
		$V_{CC} = 2.7V$; $I_{OH} = -12mA$	2.2		
		$V_{CC} = 3.0V$; $I_{OH} = -18mA$	2.4		
		$V_{CC} = 3.0V$; $I_{OH} = -24mA$	2.2		
V_{OL}	LOW Level Output Voltage	$2.7V \leq V_{CC} \leq 3.6V$; $I_{OL} = 100\mu A$		0.2	V
		$V_{CC} = 2.7V$; $I_{OL} = 12mA$		0.4	
		$V_{CC} = 3.0V$; $I_{OL} = 16mA$		0.4	
		$V_{CC} = 3.0V$; $I_{OL} = 24mA$		0.55	

1. These values of V_I are used to test DC electrical characteristics only. Functional test should use $V_{IH} \geq 2.4V$, $V_{IL} \leq 0.5V$.

MC74LCX157

DC ELECTRICAL CHARACTERISTICS (continued)

Symbol	Characteristic	Condition	T_A = –40°C to +85°C		Unit
			Min	Max	
I_I	Input Leakage Current	2.7V ≤ V_{CC} ≤ 3.6V; 0V ≤ V_I ≤ 5.5V		±5.0	μA
I_{CC}	Quiescent Supply Current	2.7 ≤ V_{CC} ≤ 3.6V; V_I = GND or V_{CC}		10	μA
		2.7 ≤ V_{CC} ≤ 3.6V; 3.6 ≤ V_I ≤ 5.5V		±10	μA
ΔI_{CC}	Increase in I_{CC} per Input	2.7 ≤ V_{CC} ≤ 3.6V; V_{IH} = V_{CC} – 0.6V		500	μA

AC CHARACTERISTICS[1] (t_R = t_F = 2.5ns; C_L = 50pF; R_L = 500Ω)

Symbol	Parameter	Waveform	Limits			Unit
			T_A = –40°C to +85°C			
			V_{CC} = 3.0V to 3.6V		V_{CC} = 2.7V	
			Min	Max	Max	
t_{PLH} t_{PHL}	Propagation Delay In to Zn	1	1.5 1.5	5.8 5.8	6.3 6.3	ns
t_{PLH} t_{PHL}	Propagation Delay S to Zn	1,2	1.5 1.5	7.0 7.0	8.0 8.0	ns
t_{PLH} t_{PHL}	Propagation Delay E to Zn	2	1.5 1.5	7.0 7.0	8.0 8.0	ns
t_{OSHL} t_{OSLH}	Output–to–Output Skew (Note 2)			1.0 1.0		ns

1. These AC parameters are preliminary and may be modified prior to release. The maximum AC limits are design targets. Actual performance will be specified upon completion of characterization.
2. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH–to–LOW (t_{OSHL}) or LOW–to–HIGH (t_{OSLH}); parameter guaranteed by design.

DYNAMIC SWITCHING CHARACTERISTICS

Symbol	Characteristic	Condition	T_A = +25°C			Unit
			Min	Typ	Max	
V_{OLP}	Dynamic LOW Peak Voltage[1]	V_{CC} = 3.3V, C_L = 50pF, V_{IH} = 3.3V, V_{IL} = 0V		0.8		V
V_{OLV}	Dynamic LOW Valley Voltage[1]	V_{CC} = 3.3V, C_L = 50pF, V_{IH} = 3.3V, V_{IL} = 0V		0.8		V

1. Number of outputs defined as "n". Measured with "n–1" outputs switching from HIGH–to–LOW or LOW–to–HIGH. The remaining output is measured in the LOW state.
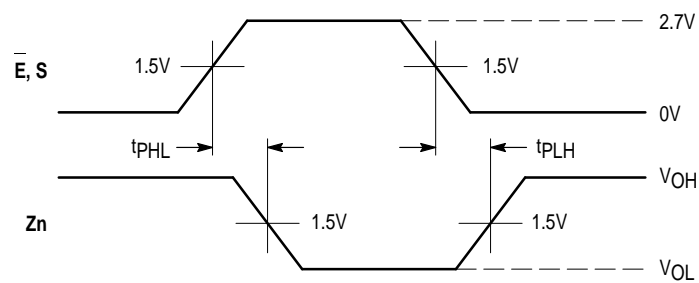
CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C_{PD}	Power Dissipation Capacitance	10MHz, V_{CC} = 3.3V, V_I = 0V or V_{CC}	25	pF
C_{IN}	Input Capacitance	V_{CC} = 3.3V, V_I = 0V or V_{CC}	7	pF
C_{OUT}	Output Capacitance	V_{CC} = 3.3V, V_I = 0V or V_{CC}	8	pF
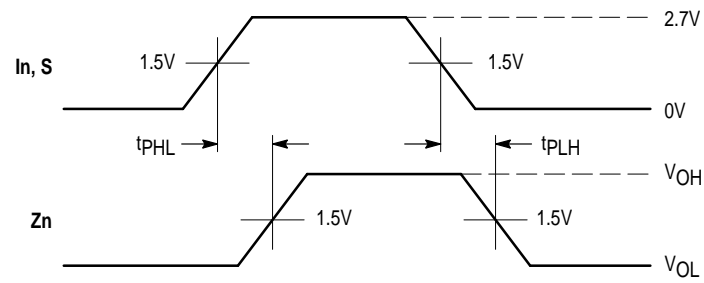
WAVEFORM 1 – NON–INVERTING PROPAGATION DELAYS
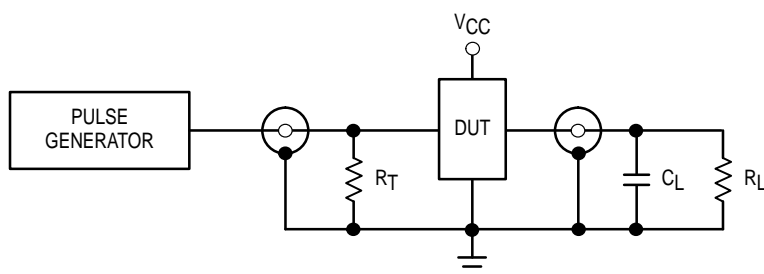$t_R = t_F$ = 2.5ns, 10% to 90%; f = 1MHz; t_W = 500ns

WAVEFORM 2 – INVERTING PROPAGATION DELAYS
$t_R = t_F$ = 2.5ns, 10% to 90%; f = 1MHz; t_W = 500ns

Figure 1. AC Waveforms

C_L = 50pF or equivalent (Includes jig and probe capacitance)
$R_L = R_1$ = 500Ω or equivalent
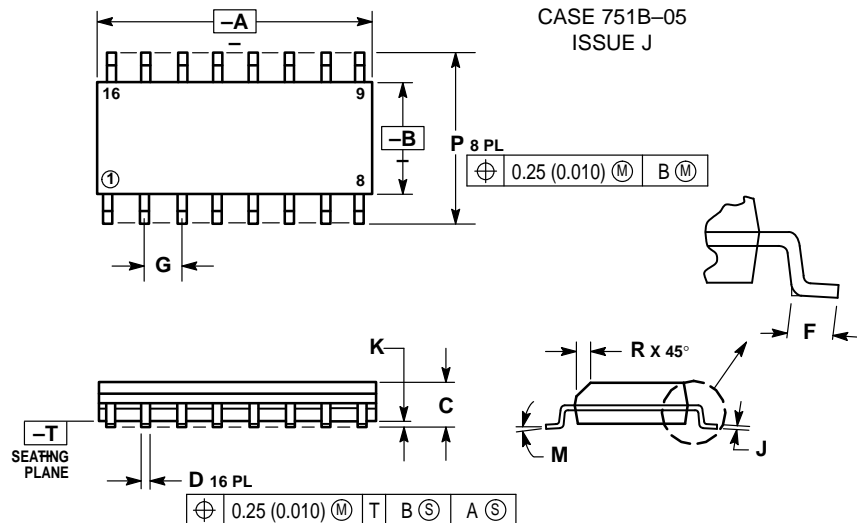$R_T = Z_{OUT}$ of pulse generator (typically 50Ω)

Figure 2. Test Circuit

MC74LCX157

OUTLINE DIMENSIONS

D SUFFIX
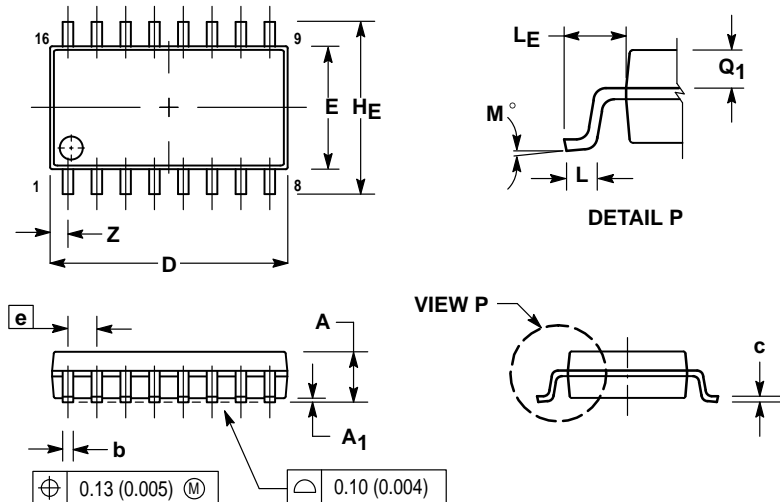PLASTIC SOIC PACKAGE
CASE 751B–05
ISSUE J

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
---	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

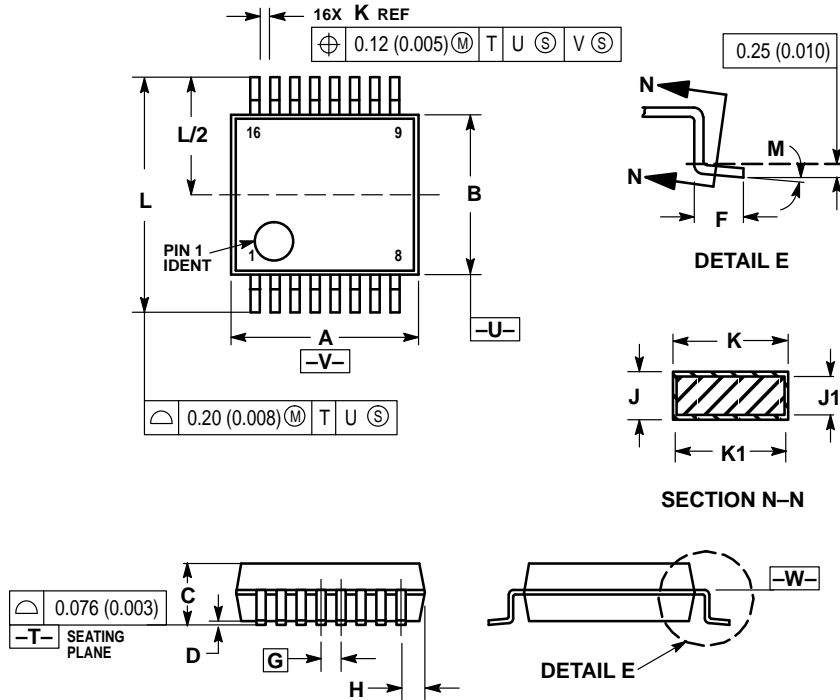**M SUFFIX**
PLASTIC SOIC EIAJ PACKAGE
CASE 966–01
ISSUE O

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
---	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A$_1$	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H$_E$	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L$_E$	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q$_1$	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

OUTLINE DIMENSIONS

SD SUFFIX
PLASTIC SSOP PACKAGE
CASE 940B–03
ISSUE B

16X **K** REF

⊕ | 0.12 (0.005) Ⓜ | T | U Ⓢ | V Ⓢ

L/2

16   9

L

B

PIN 1
IDENT   1   8

A

–U–
–V–

△ | 0.20 (0.008) Ⓜ | T | U Ⓢ

0.25 (0.010)

DETAIL E

N
N
M
F

K
J   J1
K1

SECTION N–N

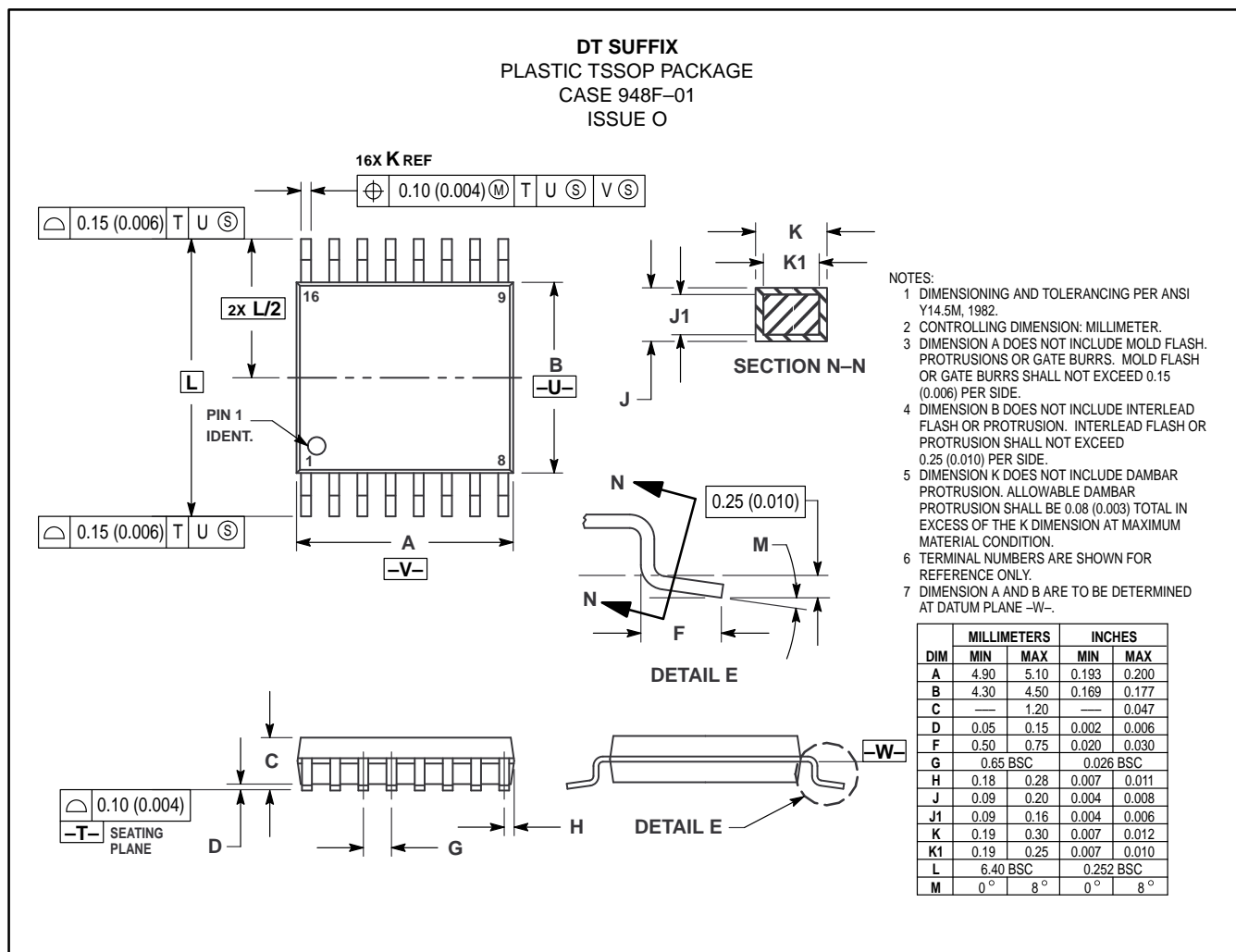△ | 0.076 (0.003)
–T– | SEATING
PLANE

C
D
G
H

DETAIL E

–W–

NOTES:
6 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
7 CONTROLLING DIMENSION: MILLIMETER.
8 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
9 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
10 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF K DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR INTRUSION SHALL NOT REDUCE DIMENSION K BY MORE THAN 0.07 (0.002) AT LEAST MATERIAL CONDITION.
11 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
12 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.07	6.33	0.238	0.249
B	5.20	5.38	0.205	0.212
C	1.73	1.99	0.068	0.078
D	0.05	0.21	0.002	0.008
F	0.63	0.95	0.024	0.037
G	0.65 BSC		0.026 BSC	
H	0.73	0.90	0.028	0.035
J	0.09	0.20	0.003	0.008
J1	0.09	0.16	0.003	0.006
K	0.25	0.38	0.010	0.015
K1	0.25	0.33	0.010	0.013
L	7.65	7.90	0.301	0.311
M	0 °	8 °	0 °	8 °

OUTLINE DIMENSIONS

DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948F–01
ISSUE O

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	—	1.20	—	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

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